

MPSOC'18 FORUM REGISTRATION FORM

For registration **before May 31**, the fees are 1400 USD for regular attendees, 1190 USD for IEEE and EDAA members and 850 USD for Speakers. Each speaker is allowed to invite a Junior attendee (student or engineer) with an additional fee of 790 USD. The fee will cover the documentation, the lunch for five days, dinner for four days including the social dinner.

Please mail or fax this form to: MPSOC'18 – MP Associates Inc., 1721 Boulder St. Ste. 107, Louisville, CO 80027 - USA
 Tel: +1 (303) 530-4562 Fax: +1 (303) 530-4334

First Name _____ Last Name _____ Company _____
 Address _____ City _____ State _____ Zip _____
 Country _____ Phone _____ Fax _____ Email _____

Advance registration (before May 31, 2018) – Circle your choice(s)

Regular attendee 1400 USD	IEEE/EDAA member 1190 USD	Student/Junior 790 USD	Speaker 850 USD	2 Days 850 USD
TOTAL FEES _____ USD				

For 2 days only, please circle your choice: **Sun/Mon** **Mon/Tue** **Tue/Wed** **Wed/Thu** **Thu/Fri**

Send full payment in U.S. dollars with this form. Use a check drawn on a US bank or a major credit card. For payments from non-U.S. banks the attendee will be charged a collection fee of US \$30.00. Purchase orders are not accepted. Use your credit card if registering by fax. Make U.S. checks payable to MPSoC.

Form of payment:

Check ___ Credit card ___ Visa ___ Mastercard ___ American Express ___ Card # _____ Exp. date _____
 Name (as it appears on card) _____ Signature _____

Refunds:

Requests for refunds received before May 31, 2018 will be subjected to a \$50 processing fee. No refunds will be made for cancellations received after May 31, 2018 and all registration fees will be forfeited. Register early to avoid disappointment.

MPSoC'18 HOTEL BOOKING



MPSoC'18 will be held in Snowbird, USA From July 29 to August 3 2018

The Cliff Lodge
 9320 South Cliff Lodge Dr
 Snowbird, UT, 84092, USA

Further information is available at: <http://www.mpsoc-forum.org/>



**18th International Forum on
MPSoC for Software-defined Hardware
July 29 - August 3, 2018, The Cliff Lodge, Snowbird, UT, USA**

<p>FOCUS</p>	<p>Multicore and Multiprocessor SoC (MPSoC) started a new computing era but brought a twofold challenge: building HW easy to use by SW designers and building SW that fully exploits HW capabilities. The main domains addressed at MPSoC are related to adapting HW and SW for better cost, performances and energy efficiency of next generation computing systems. Emerging SW and HW design technologies and architectures combined with advanced semiconductor manufacturing technologies are explored to build energy efficient Manycore and many IP architectures serving advanced computing (image, vision, and cloud) and distributed networked systems.</p>	<p>General Chair: Pierre-Emmanuel Gaillardon, <i>University of Utah, USA</i></p> <p>Program Co-Chairs: Anca Molnos, <i>CEA-LETI, France</i> Yoshinori Takeuchi, <i>Osaka University, Japan</i> Jishen Zhao, <i>UC San Diego, USA</i></p> <p>European Liaison Frédéric Petrot, <i>TIMA-INP Grenoble, France</i> Nicolas Ventroux, <i>CEA-LIST, France</i></p> <p>North American Liaison: Gabriela Nicolescu, <i>Poly. Montreal, Canada</i></p> <p>Asian Liaison: Shinya Takamaeda-Yamazaki, <i>Hokkaido University, Japan</i> Sungjoo Yoo, <i>Seoul National University, Korea</i></p> <p>Industry Liaison: Andreas Herkersdorf, <i>TUM, Germany</i> Yoshifumi Sakamoto, <i>IBM, Japan</i> Yuan Xie, <i>UC Santa Barbara, USA</i></p> <p>Local Organization Chair: Tom Becnel, <i>University of Utah, USA</i></p> <p>Finance Chair: Frédéric Rousseau, <i>TIMA-UGA, France</i> Ken Stevens, <i>University of Utah, USA</i></p> <p>Publicity Chair: Fabien Clermidy, <i>CEA-LETI, France</i> Koji Inoué, <i>Kyuchu University, Japan</i></p> <p>Proceedings Chair: Tom Becnel, <i>University of Utah, USA</i></p> <p>Web Chair: Edouard Giacomini, <i>University of Utah, USA</i></p> <p>Technical Program Committee: Marcello Coppola, <i>STMicroelectronics, France</i> Raphaël David, <i>CEA-List, France</i> Giovanni De Micheli, <i>EPFL, Switzerland</i> Rolf Ernst, <i>TU Braunschweig, Germany</i> John Goodacre, <i>ARM, UK</i> Kees Goossens, <i>TUE, The Netherlands</i> Masaharu Imai, <i>Osaka University, Japan</i> Koji Inoue, <i>Kyushu University, Japan</i> Tsuyoshi Isshiki, <i>Tokyo Institute of Tech., Japan</i> Ahmed Jerraya, <i>CEA-Leti, France</i> Rainer Leupers, <i>RWTH Aachen Univ., Germany</i> Youn-long Lin, <i>National Tsing Hua Univ., Taiwan</i> Takashi Miyamori, <i>Toshiba Corp., Japan</i> Gabriela Nicolescu, <i>Poly. Montreal, Canada</i> Pierre Paulin, <i>Synopsys, Canada</i> Frédéric Pétrot, <i>TIMA-INPG, France</i> Yoshinori Takeuchi, <i>Osaka University, Japan</i> Hiroyuki Tomiyama, <i>Ritsumeikan Univ., Japan</i> Kees Vissers, <i>Xilinx, USA</i> Norbert Wehn, <i>Univ. of Kaiserslautern, Germany</i> Marilyn Wolf, <i>Georgia Institute of Tech., USA</i> Yuan Xie, <i>UC Santa Barbara, USA</i> Hiroyuki Yasuura, <i>Kyushu University, USA</i> Sungjoo Yoo, <i>Seoul National University, Korea</i></p>
<p>CONTENTS</p>	<p>MPSOC is an interdisciplinary forum bringing together key R&D actors from the different fields required to design Multicore and multiprocessor HW and SW systems. The program brings together experts in major HW and SW architectures (Processor, Memory, I/O, Interconnect, RTOS, GFX, Virtualization, application-(domain) specific acceleration & system architectures), design technologies (parallel programming, rapid prototyping, system design models and tools) and emerging semiconductor technologies (heterogeneous integration, 3D, photonics) to build next-generation thinking that will bridge the gap between HW and SW. More than 50 world class R&D speakers will discuss fundamental and strategic issues to master Software-defined Hardware for energy-efficient and high-performance computing. The program includes keynotes on major HW and SW trends and technical sessions to present strategic directions and state-of-the-art research. The 5-day program will also include in-depth technology challenge presentations and short keynotes followed by insightful panels. All the talks will be given by CTO-level speakers from Industry and world-class professors from Academia.</p>	
<p>WHY ATTEND</p>	<p>Thanks to its full week format and the high quality of both attendees and speakers, MPSOC is a unique opportunity for executives and senior managers to explore new ideas and refine strategic thinking. MPSOC is the single best event in the world that brings together so many leading thinkers on the future of HW and SW design. It enables great informal networking and interactions with experienced, distinguished researchers and top academic and industrial experts. It builds bridges between different technical areas and corporations/institutes/countries. Finally, it is a unique environment for anyone who wants to share knowledge with researchers and key managers from industry.</p>	
<p>FEE</p>	<p>For registration before May 31, the fee amounts to 1400 USD for regular attendees, 1190 USD for IEEE and EDAA members, and 850 USD for speakers. Each speaker is allowed to invite Junior attendee (student) with a fee of 790 USD. It will cover the documentation, the lunch for five days, dinner for four days including the social dinner.</p>	

18th International Forum on MPSoC for Software-defined Hardware

July 29 - August 3, 2018, The Lodge at Snowbird, Snowbird, UT, 84092, USA

KEYNOTES (6)

- Rob Aitken, *ARM, UK*
- Vance Checketts, *Dell EMC, USA*
- Paul Joyce, *Dell EMC, USA*
- Ike Nassi, *TidalScale, US*
- Shuichi Yamane, *Socionext Inc., Japan*
- Farhang Yazdani, *Broadpak, US*

IN-DEPTH PRESENTATIONS (9)

- Gerhard Fettweis, *TU Dresden, Germany*
- Masatoshi Ishii, *IBM Research - Tokyo, Japan*
- K. Charles Janac, *Arteris Inc., USA*
- Shahar Kvatinisky, *Technion, Israël*
- Francois Neumann, *Safran Electronics & Defense, France*
- Greg Nielson, *Nielson Scientific, USA*
- Pei-Lin Pai, *Winbond, Taiwan*
- Pierre Paulin, *Synopsys, Canada*
- Yankin Tanurhan, *Synopsys, USA*

MINI-KEYNOTES (45)

- Gerd Ascheid, *RWTH Aachen University, Germany*
- Fumio Arakawa, *The University of Tokyo, Japan*
- Kees van Berkel, *Ericsson, Eindhoven University of Technology, The Netherlands*
- Rolf Ernst, *Technische Universität Braunschweig, Germany*
- Ran Ginosar, *Technion-Israel Institute of Technology, Israël*
- Masaki Gondo, *eSOL Co.,Ltd., Japan*
- John Goodacre, *ARM, UK*
- Arnaud Grasset, *Thales Research & Tech., France*
- Victor Grimblatt, *Synopsys Chile R&D Center, Latin America*
- Yuko Hara-Azumi, *Tokyo Institute of Technology, Japan*
- Andreas Herkersdorf, *TU Munich, Germany*
- Koji Inoue, *Kyushu University, Japan*
- Tohru Ishihara, *Kyoto University, Japan*

MINI-KEYNOTES

- Tsuyoshi Isshiki, *Tokyo Institute of Technology, Japan*
- Masaaki Kondo, *The University of Tokyo, Japan*
- Youn-Long Lin, *National Tsing Hua University, Taiwan*
- Hiroki Matsutani, *Keio University, Japan*
- Pankaj Mehra, *Western Digital Corporation, USA*
- Takashi Miyamori, *Toshiba Corporation, Japan*
- Anca Molnos, *CEA-Leti, France*
- Eric Monchalain, *ATOS, France*
- Yuichi Nakamura, *NEC Corp., Japan*
- Gabriela Nicolescu, *Ecole Polytechnique de Montréal, Canada*
- Danilo Pau, *STMicroelectronics, Italy*
- Frédéric Pétrot, *TIMA Lab, Grenoble University, France*
- Frédéric Rousseau, *TIMA Lab, Grenoble University, France*
- Yoshifumi Sakamoto, *IBM Japan, Japan*
- Tsuyoshi Sato, *PIONEER, Japan*
- Weihua Sheng, *Silexica, Germany*
- Akihiko Shinya, *NTT Nanophotonics Center, Japan*
- Shinya Takamaeda, *Hokkaido University, Japan*
- Yoshinori Takeuchi, *Osaka University, Japan*
- Ittetsu Taniguchi, *Graduate School of Information Science and Technology Osaka University, Japan*
- Hiroyuki Tomiyama, *Ritsumeikan University, Japan*
- Nicolas Ventroux, *CEA-List, France*
- Kees Vissers, *Xilinx, USA*
- Norbert Wehn, *University of Kaiserslautern, Germany*
- Marilyn Wolf, *Georgia Tech, USA*
- Yuan Xie, *UCSB, USA*
- Jiang Xu, *Hong Kong University of Science and Technology, Hong Kong*
- Koichiro Yamashita, *Fujitsu Laboratories LTD., Japan*
- Song Yao, *DeePhi Tech, China*
- Sungjoo Yoo, *Seoul National University, Korea*
- Wei Zhang, *Hong Kong University of Science and Technology, Hong Kong*
- Jishen Zhao, *UCSD, USA*

Total speakers: 60